

Title (en)

METHOD FOR MACHINING THE SURFACE OF A WAFER FOR PRODUCING A SOLAR CELL, AND WAFER

Title (de)

VERFAHREN ZUR BEARBEITUNG DER OBERFLÄCHE EINES WAFERS ZUR HERSTELLUNG EINER SOLARZELLE UND WAFER

Title (fr)

PROCÉDÉ POUR USINER LA SURFACE D'UNE PLAQUETTE DESTINÉE À PRODUIRE UNE CELLULE PHOTOVOLTAÏQUE ET PLAQUETTE

Publication

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Application

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Priority

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- DE 102008063558 A 20081208

Abstract (en)

[origin: US2011232751A1] In a method for the treatment of the surface of a wafer for producing a solar cell, onto which wafer an antireflection and passivation layer has been applied onto a p-doped layer in a step preceding the method, the surface is treated in a processing step and then a subsequent metallization on the surface of the wafer for producing contacts for the solar cell takes place. This processing step is for passivation or for removal of the p-doped layer in the region of disturbances such as scratches, defect sites, pinholes and inhomogeneous regions in the antireflection and passivation layer. It is thus possible to avoid metal depositions at these disturbances.

IPC 8 full level

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CPC (source: EP KR US)

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